



(2,16mm) .085"

DPAM, DPAF SERIES

HIGH DENSITY DIFFERENTIAL PAIR ARRAY

DPAM Mates with:
DPAF, RDPAF

DPAF Mates with:
DPAM

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?DPAM or www.samtec.com?DPAF

Insulator Material:

Black LCP

Contact Material:

Copper Alloy

Plating:

Au over 50µ" (1,27µm) Ni

Current Rating (2x3):

2.9A @ 30°C Temperature Rise

Operating Temp Range:

-55°C to +125°C

Contact Resistance:

10.4mΩ max

Working Voltage:

300 VAC

Mated Cycles:

100 Cycles

RoHS Compliant:

Yes

Lead-Free Solderable:

Yes



Protocols Supported

- Fibre Channel
- Rapid I/O
- PCI Express®
- SATA
- Infiniband
- XAUI
- MGT (Rocket I/O)

Download app notes at www.samtec.com/appnote
Contact SIG @ samtec.com for questions on protocols

| DPAM | PAIRS PER ROW | LEAD STYLE | PLATING OPTION | NO. OF ROWS | SOLDER TYPE | A | OPTION |
|------|--|-------------------------------|---|---|--|---|---|
| | -04, -06 (-07.0 only) -08, -15, -23 (All lead styles) | Specify LEAD STYLE from chart | -S =30µ" (0,76µm) Gold on contact area, Tin on solder tail (-11 & -14 only) -H =30µ" (0,76µm) Gold on contact area, Gold Flash on solder tail (-07 only) | -8 =Eight Pair Rows -3 =Three Pair Rows (-07 only) | -2 = Lead-Free Tin Alloy 96.5% Sn/ 3% Ag/.5% Cu Solder Crimp | | -K =(20,00mm) 0.80" DIA Polyimide film Pick & Place Pad -TR =Tape & Reel -GP =Guide Post (-23 only & -07 only) |

Perimeter Grounds (TYP)

Signal Pairs (TYP)

02 01 G2 03 04

No. of positions x (2,16) .085 + (4,34) .171

(2,54) .100

(2,54) .100

(1,27) .050

(1,08) .0425

(1,27) .050 DIA

No. of positions x (2,16) .085 + (2,95) .116

| LEAD STYLE | A |
|------------|--------------|
| -07.0 | (6,66) .262 |
| -11.0 | (10,72) .422 |
| -14.0 | (13,66) .538 |

| NO OF ROWS | B |
|------------|--------------|
| -8 | (24,59) .968 |
| -3 | (11,89) .468 |

| | |
|--|----------------------------|
| Staggered pitch DPAM/DPAF | Rated @ 3dB Insertion Loss |
| 10mm Stack Height | |
| Differential Pair Signaling | 7.0 GHz / 14.0 Gbps |
| Performance data for other stack heights and complete test data available at www.samtec.com?DPAM , www.samtec.com?DPAF or contact sig@samtec.com | |

| DPAF | PAIRS PER ROW | 03.0 | PLATING OPTION | NO. OF ROWS | SOLDER TYPE | A | OPTION |
|------|-------------------------|------|--|--|--|---|---|
| | -04, -06, -08, -15, -23 | | -H =30µ" (0,76µm) Gold on contact area, Gold Flash on solder tail | -8 =Eight Pair Rows -3 =Three Pair Rows | -2 = Lead-Free Tin Alloy 96.5% Sn/ 3%Ag/ .5% Cu Solder Crimp | | -K =(20,00mm) 0.80" DIA Polyimide film Pick & Place Pad -TR =Tape & Reel |

Perimeter Grounds (TYP)

Signal Pairs (TYP)

04

02 (2,54)

01

03

No. of positions x (2,16) .085 + (4,34) .171

(1,52) .060

(1,27) .050

(1,27) .050

(1,08) .0425

(1,27) .050 DIA

No. of positions x (2,16) .085 + (2,95) .116

| NO OF ROWS | A |
|------------|--------------|
| -8 | (23,32) .918 |
| -3 | (10,62) .418 |

| SIZE | USABLE PAIRS PER ARRAY* |
|----------|-------------------------|
| -08 x -8 | 48 Pairs |
| -15 x -8 | 104 Pairs |
| -23 x -8 | 168 Pairs |
| -08 x -3 | 18 Pairs |
| -15 x -3 | 39 Pairs |
| -23 x -3 | 63 Pairs |

| DPAM LEAD STYLE | DPAF MATED HEIGHT* |
|-----------------|--------------------|
| -07.0 | 10mm |
| -11.0 | 14mm |
| -14.0 | 17mm |

*Assumes first and last pair in each row are grounded

*Processing conditions will affect mated height.

ALSO AVAILABLE

Tin-Lead Solder Charge.
Call Samtec.

Note: Other Gold plating options available. Contact Samtec.

Note: Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM